

Board Level Cooling – Surface Mount 7109



BOARD LEVEL COOLING - Surface Mount 7109

Surface Mount 7109 is a surface mount board level heat sink designed to cool Dual Flat No-Leads (DFN) packages, Quad Flat No-Leads (QFN) packages and D2 Pak (TO-263) devices. Surface Mount 7109 can cool either a single D2 Pak, larger QFNs or DFNs, or multiple QFNs or DFNs. The tin plated surface of Surface Mount 7109 enables direct soldering to Printed Circuit Boards (PCBs) for effective board cooling. This part is also offered in tape and reel as indicated by the /TR at the end of the part number. Representative image only.



ORDERING INFORMATION

Part Number	Device Type
7109DG	QFN, DFN, D2 Pak (TO-263)
7109DG/TR	QFN, DFN, D2 Pak (TO-263)

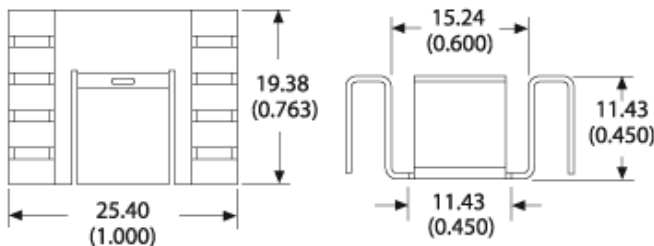
HEAT SINK DETAILS

Property	Details
Material	Copper
Finish	Tin-Plated
Device Attachment Options	-
Thermal Interface Material	-

Property	Details
Heat Sink Width (mm)	25.40
Heat Sink Length (mm)	19.38
Heat Sink Height (mm)	11.43
Heat Sink Mounting Direction	Horizontal

MECHANICAL & PERFORMANCE

Drawing dimensions are shown in mm, (in)



Recommended copper pad size for heat sink and device mounting footprint

